

Features

- Reduced ultra-low forward voltage drop (VF). Better efficiency and cooler operation
- Reduced high temperature reverse leakage. Increased reliability against thermal runaway failure in high temperature operation
- Totally Lead-Free & Fully RoHS Compliant
- Halogen and Antimony Free. "Green" Device

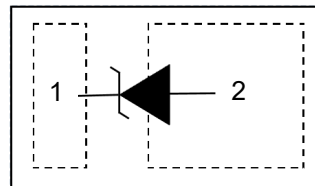
Mechanical Characteristics

- Case: U-DFN1608-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.002 grams (Approximate)

Marking Information

- DC-DC Converters
- AC-DC Adaptors

Marking Information



Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Value	Units
Peak Repetitive Reverse Voltage	V _{RRM}	40	V
Working Peak Reverse Voltage	V _{RWM}	40	V
DC Blocking Voltage	V _{RM}	40	V
Average Rectified Output Current	I _O	1	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	8	A
Repetitive Peak Forward Current (tp = 1ms, duty cycle = 25%)	I _{FRM}	5	A
Typical Thermal Resistance	R _{θJA}	130	°C/W
Junction Temperature	T _J	-65 to +150	°C
Storage Temperature	T _{STG}	-65 to +150	°C

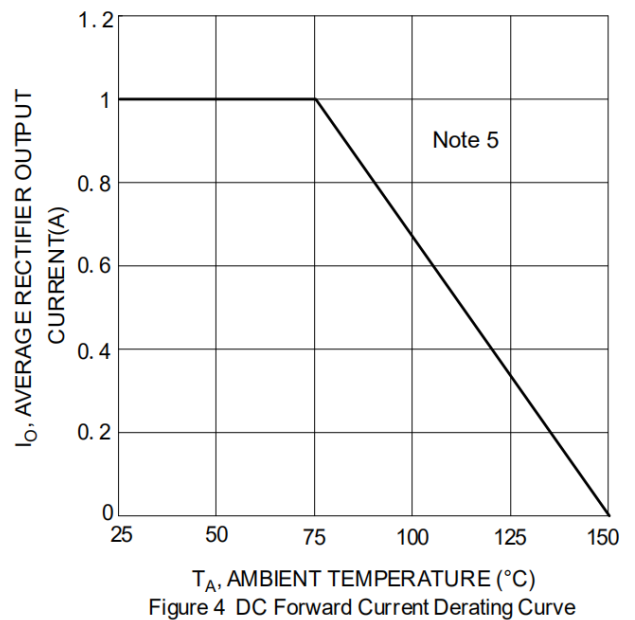
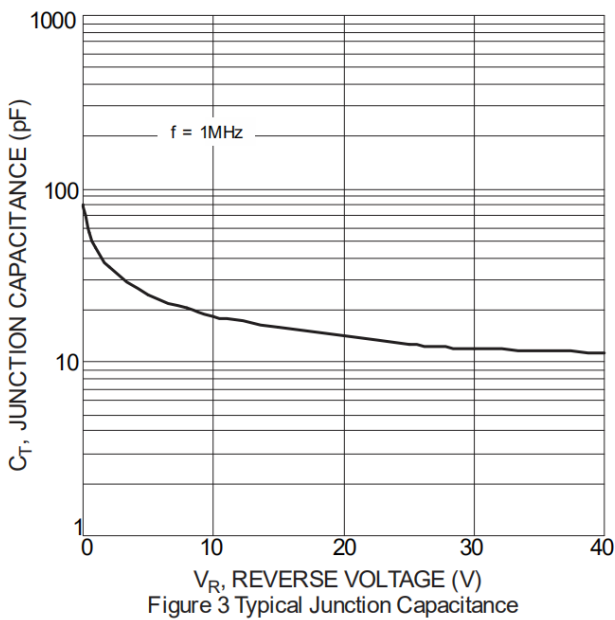
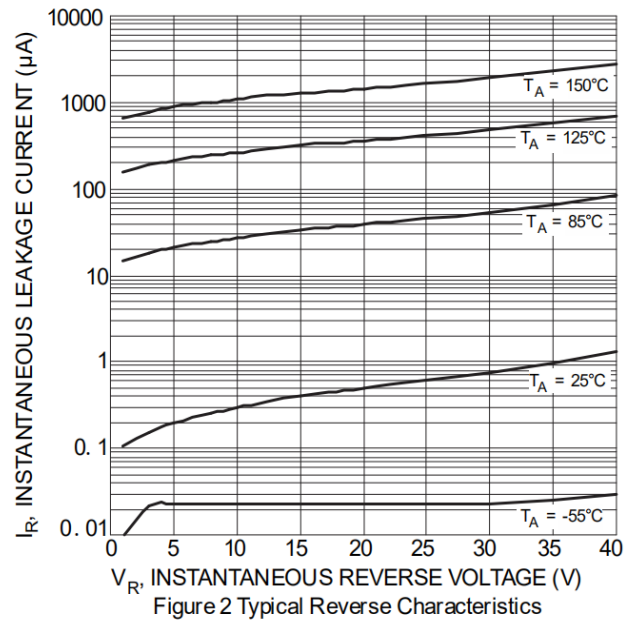
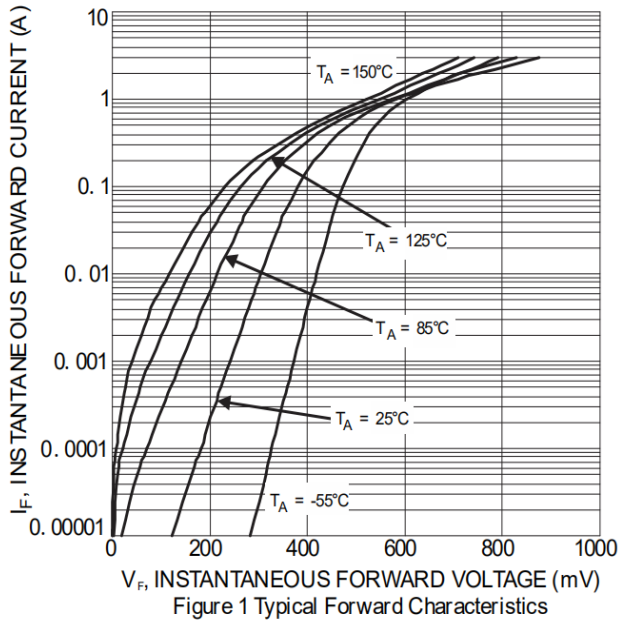
Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min	TYP	Max	Unit	Test Condition
Leakage Current	I_R		0.0006	0.004	mA	$V_R = 10\text{V}, T_J = +25^\circ\text{C}$
			0.002	0.02		$V_R = 40\text{V}, T_J = +25^\circ\text{C}$
			0.80			$V_R = 40\text{V}, T_J = +125^\circ\text{C}$
Forward Voltage Drop	V_F		0.49	0.56	V	$I_F = 0.5\text{A}, T_J = +25^\circ\text{C}$
			0.42			$I_F = 0.5\text{A}, T_J = +125^\circ\text{C}$
			0.59	0.66		$I_F = 1\text{A}, T_J = +25^\circ\text{C}$
			0.55			$I_F = 1\text{A}, T_J = +125^\circ\text{C}$
Total Capacitance	C_T		25		pF	$V_R=5\text{V}, f=1\text{MHz}$
Reverse Recovery Time	t_{rr}		8.4		ns	$I_F = 10\text{mA}, I_{rrm} = 0.1I_r, T_a = +25^\circ\text{C}$

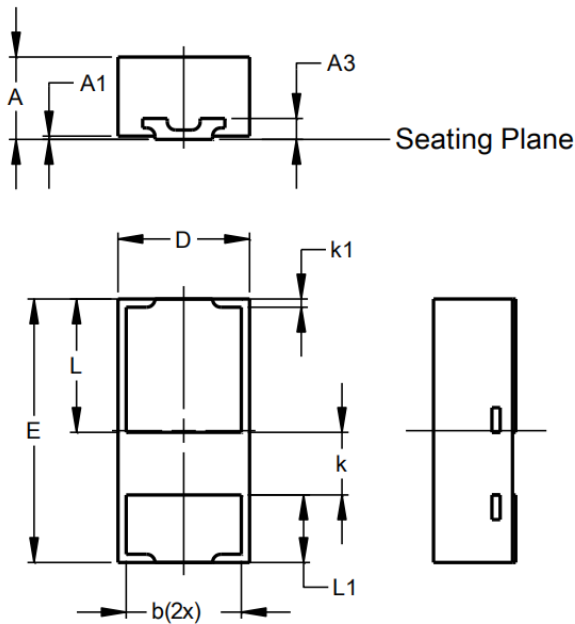
Notes:

1. Test with FR-4 PC board 1-inch sq. copper pad, 2oz.
2. Short duration pulse test used to minimize self-heating effect.

Typical Characteristics

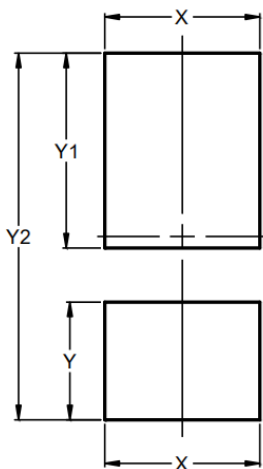


DFN1006-2 Package Outline Drawing



U-DFN1608-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.02
A3	-	-	0.127
b	0.65	0.75	0.70
D	0.75	0.85	0.80
E	1.55	1.65	1.60
k	0.38 BSC		
k1	0.05 BSC		
L	0.76	0.86	0.81
L1	0.36	0.46	0.41
All Dimensions in mm			

Suggested Land Pattern



Dimensions	Value (in mm)
X	0.800
Y	0.610
Y1	1.010
Y2	1.900

Contact Information

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